

6 A, 600 V, Hyperfast Diode

The RHRD660S9A is a hyperfast diodes with soft recovery characteristics. It has the half recovery time of Ultrafast diodes and is silicon nitride passivated ionimplanted epitaxial planar construction. These devices are intended to be used as freewheeling/clamping diodes and Diodes in a variety of switching power supplies and other power switching applications. Their low stored charge and hyperfast soft recovery minimize ringing and electrical noise in many power switching circuits reducing power loss in the switching transistors.

Ordering Information

PART NUMBER	PACKAGE	BRAND
RHRD660S	TO-252-3L	RHR660

Symbol



Features

- Hyperfast Recovery $t_{rr} = 35$ ns (@ $I_F = 6$ A)
- Max Forward Voltage, $V_F = 2.6$ V (@ $T_C = 25^\circ\text{C}$)
- 600 V Reverse Voltage and High Reliability
- Avalanche Energy Rated
- RoHS compliant

Applications

- Switching Power Supplies
- Power Switching Circuits
- General Purpose

Packaging

JEDEC STYLE TO-252



Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, Unless Otherwise Specified

	RATING	UNIT
Peak Repetitive Reverse Voltage	V_{RRM}	V
Working Peak Reverse Voltage	V_{RWM}	V
DC Blocking Voltage	V_R	V
Average Rectified Forward Current	$I_{F(AV)}$	A
($T_C = 152^\circ\text{C}$)		
Repetitive Peak Surge Current	I_{FRM}	A
(Square Wave, 20 kHz)		
Nonrepetitive Peak Surge Current	I_{FSM}	A
(Halfwave, 1 Phase, 60 Hz)		
Maximum Power Dissipation	P_D	W
Avalanche Energy (See Figures 10 and 11)	E_{AVL}	mJ
Operating and Storage Temperature	T_{STG}, T_J	$^\circ\text{C}$
Maximum Lead Temperature for Soldering	T_L	$^\circ\text{C}$
(Leads at 0.063 in. (1.6 mm) from case for 10 s)	300	$^\circ\text{C}$
Package Body for 10s, see Tech Brief 334	T_{PKG}	$^\circ\text{C}$
	260	

Electrical Specifications $T_C = 25^\circ\text{C}$, Unless Otherwise Specified

SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNIT
V_F	$I_F = 6 \text{ A}$	-	-	2.1	V
	$I_F = 6 \text{ A}, T_C = 150^\circ\text{C}$	-	-	1.7	V
I_R	$V_R = 600 \text{ V}$	-	-	100	μA
	$V_R = 600 \text{ V}, T_C = 150^\circ\text{C}$	-	-	500	μA
t_{rr}	$I_F = 1 \text{ A}, dI_F/dt = 200 \text{ A}/\mu\text{s}$	-	-	30	ns
	$I_F = 6 \text{ A}, dI_F/dt = 200 \text{ A}/\mu\text{s}$	-	-	35	ns
t_a	$I_F = 6 \text{ A}, dI_F/dt = 200 \text{ A}/\mu\text{s}$	-	16	-	ns
t_b	$I_F = 6 \text{ A}, dI_F/dt = 200 \text{ A}/\mu\text{s}$	-	8.5	-	ns
Q_{rr}	$I_F = 6 \text{ A}, dI_F/dt = 200 \text{ A}/\mu\text{s}$	-	45	-	nC
C_J	$V_R = 10 \text{ V}, I_F = 0 \text{ A}$	-	20	-	pF
$R_{\theta JC}$		-	-	3	$^\circ\text{C}/\text{W}$

DEFINITIONS

V_F = Instantaneous forward voltage (pw = 300 μs , D = 2%).

I_R = Instantaneous reverse current.

T_{rr} = Reverse recovery time (See Figure 9), summation of $t_a + t_b$.

t_a = Time to reach peak reverse current (See Figure 9).

t_b = Time from peak I_{RM} to projected zero crossing of I_{RM} based on a straight line from peak I_{RM} through 25% of I_{RM} (See Figure 9).

Q_{rr} = Reverse recovery charge.

C_J = Junction capacitance.

$R_{\theta JC}$ = Thermal resistance junction to case.

pw = Pulse width.

D = Duty cycle.

Typical Performance Curves

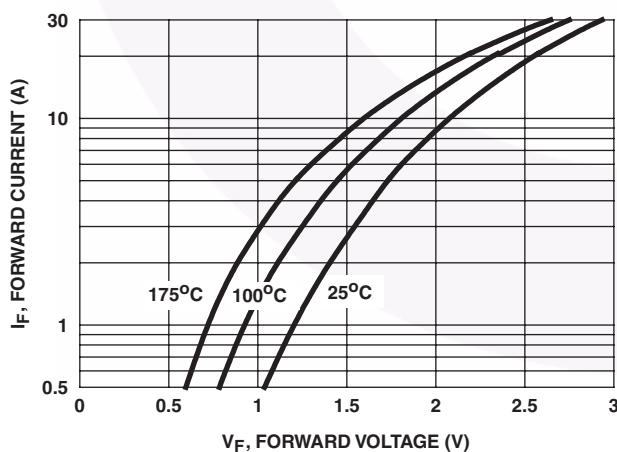


FIGURE 1. FORWARD CURRENT vs FORWARD VOLTAGE

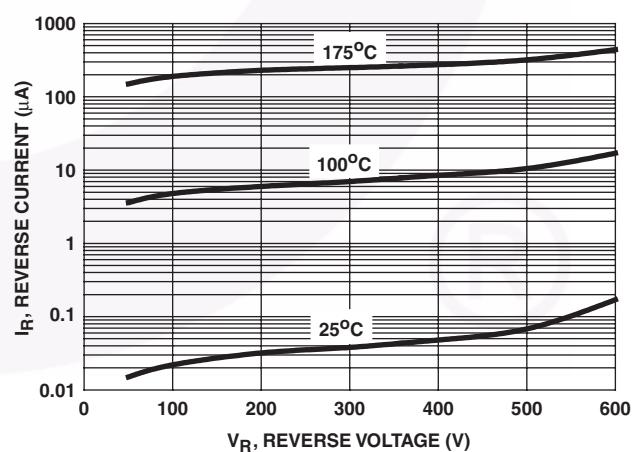


FIGURE 2. REVERSE CURRENT vs REVERSE

Typical Performance Curves (Continued)

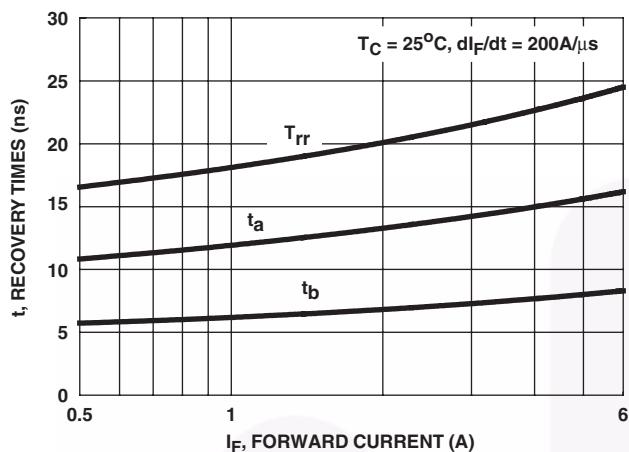


FIGURE 3. T_{rr} , t_a AND t_b CURVES vs FORWARD CURRENT

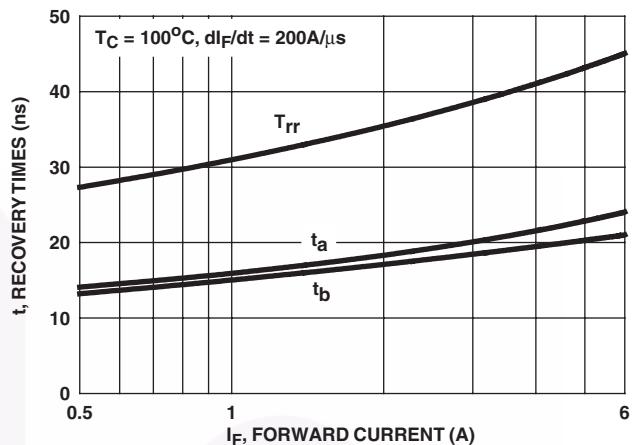


FIGURE 4. T_{rr} , t_a AND t_b CURVES vs FORWARD CURRENT

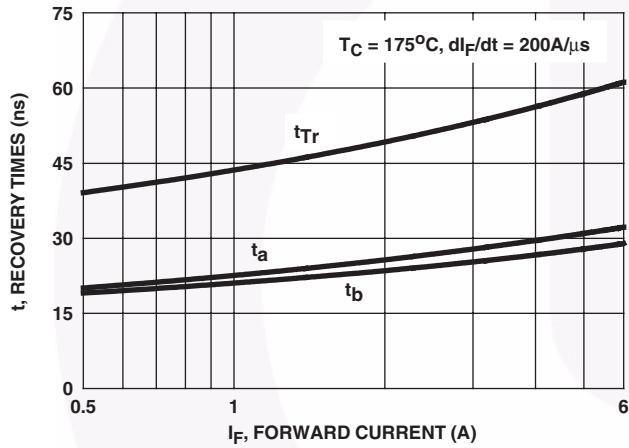


FIGURE 5. T_{rr} , t_a AND t_b CURVES vs FORWARD CURRENT

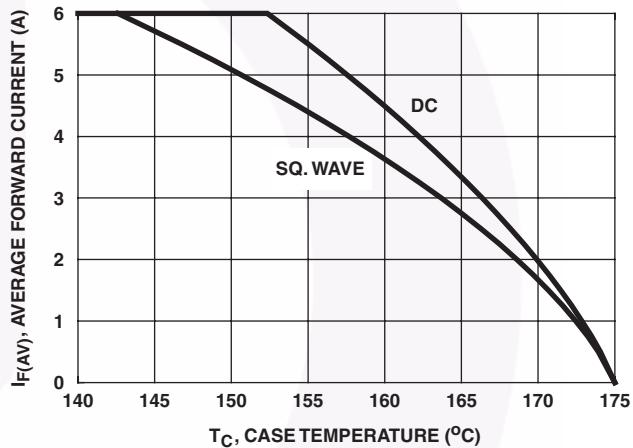


FIGURE 6. CURRENT DERATING CURVE

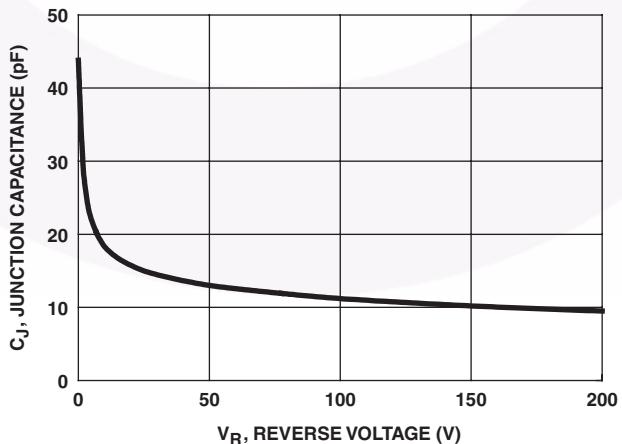
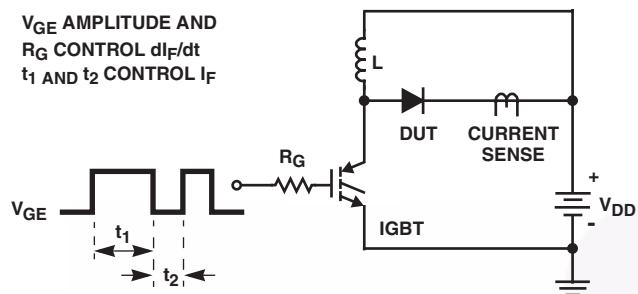
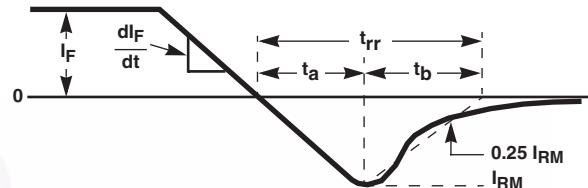


FIGURE 7. JUNCTION CAPACITANCE vs REVERSE VOLTAGE

Test Circuits and Waveforms

FIGURE 8. T_{rr} TEST CIRCUITFIGURE 9. T_{rr} WAVEFORMS AND DEFINITIONS

I_{MAX} = 1A
L = 20mH
R < 0.1Ω
E_{AVL} = 1/2L² [V_{R(AVL)}/(V_{R(AVL)} - V_{DD})]
Q₁ = IGBT (BV_{CES} > DUT V_{R(AVL)})

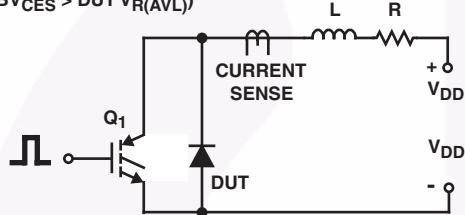


FIGURE 10. AVALANCHE ENERGY TEST CIRCUIT

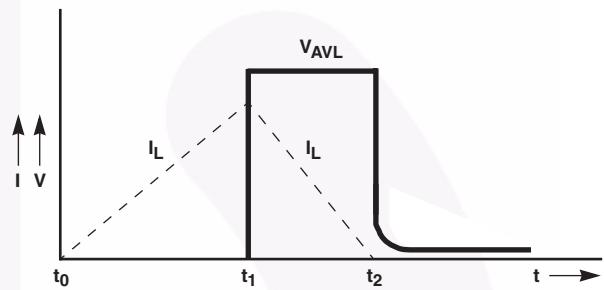


FIGURE 11. AVALANCHE CURRENT AND VOLTAGE WAVEFORMS

Mechanical Dimensions

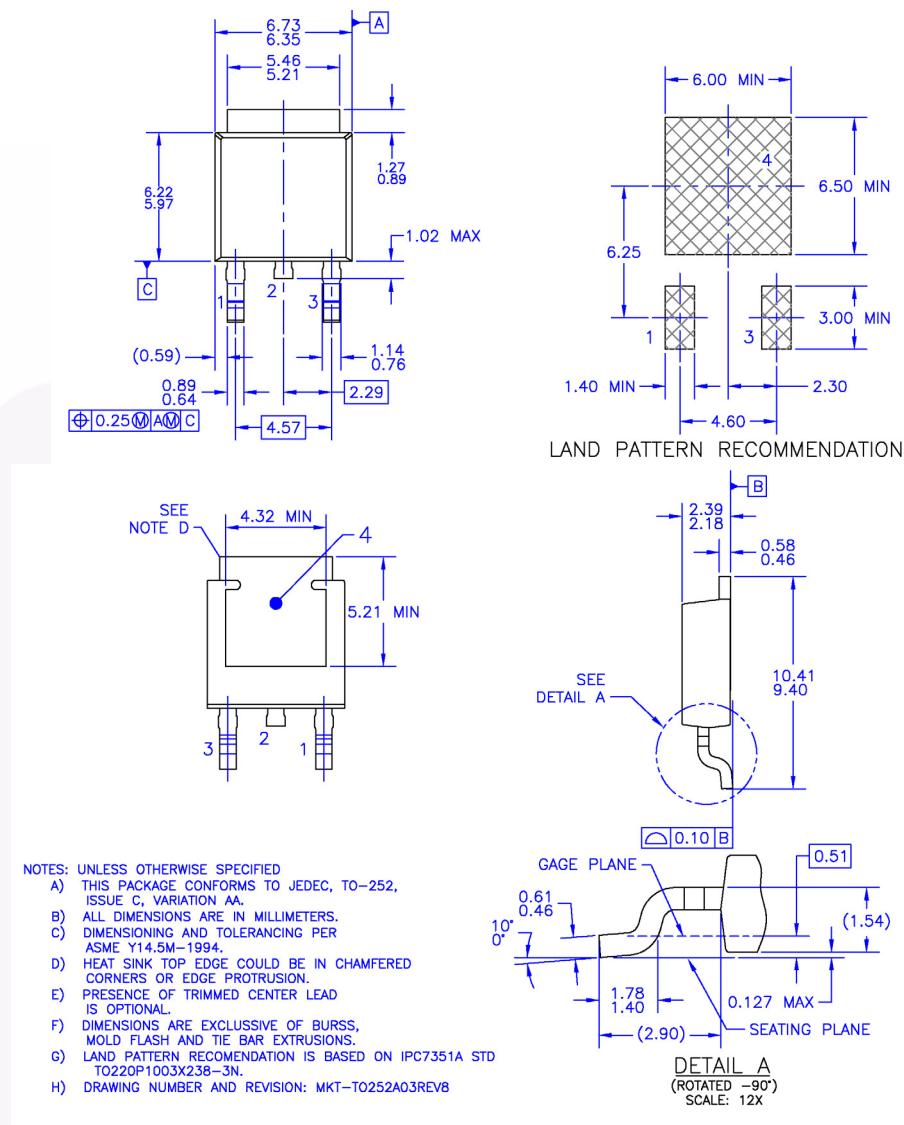


Figure 12. TO-252 3L (DPAK) - TO252 (D-PAK), MOLDED, 3 LEAD, OPTION AA&AB

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